IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A surface-mount solid electrolytic capacitor comprising:

a capacitor element;

an anode lead terminal made of a metal plate and electrically connected to an anode of the capacitor element;

a cathode lead terminal made of a metal plate and electrically connected to a cathode of the capacitor element; and

a package made of synthetic resin and hermetically sealing the capacitor element;

the anode lead terminal and the cathode lead terminal ~~terminals~~ being embedded in a bottom of the package with lower surfaces of the anode lead terminal and the cathode lead terminal ~~terminals~~ exposed at a bottom surface of the package,

wherein each of the anode lead terminal and the cathode lead terminal ~~are respectively~~ is formed with a first standing piece ~~pieces~~ at a portion ~~portions~~ corresponding to a side surface ~~surfaces~~ of the package, the first standing piece ~~pieces~~ having ~~respective~~ an outer surface ~~surfaces~~ exposed at the side surface ~~surfaces~~ of the package, the first standing piece of the anode lead terminal being spaced from the anode, and

wherein the anode lead terminal is formed with a second standing piece in contact with the anode within the resin package.

2. (Currently Amended) The surface-mount solid electrolytic capacitor according to claim 1, wherein each of the first standing pieces is formed at part of the corresponding lead terminal in a width direction.

3. (Original) A method for manufacturing a surface-mount solid electrolytic capacitor, the method comprising the steps of:

preparing a lead frame by punching a metal plate, the lead frame including a pair of side frame portions integrally connected to each other by a tie bar, one of the side frame portions being formed with an anode lead terminal while the other one of the side frame portions being formed with a cathode lead terminal;

removably bonding a tape to the lead frame so that the tape crosses the anode lead terminal, the cathode lead terminal and the tie bar;

separating the anode lead terminal and the cathode lead terminal from the respective side frame portions and then bending an end of each of the anode lead terminal and the cathode lead terminal to form a standing piece;

mounting a capacitor element onto the anode lead terminal and the cathode lead terminal so that an anode and a cathode of the capacitor element are electrically connected to the anode lead terminal and the cathode lead terminal, respectively;

molding a synthetic resin into a package for hermetically sealing the capacitor element so that the lead terminals are embedded in the package with a surface of each of the lead terminals and an outer surface of each of the standing pieces exposed; and

removing the tape.

4. (Currently Amended) A method for manufacturing a surface-mount solid electrolytic capacitor, the method comprising the steps of:

preparing a lead frame by punching a metal plate, the lead frame including a pair of side frame portions integrally connected to each other by a tie bar, one of the side frame portions being formed with an anode lead terminal while the other one of the side frame portions being formed with a cathode lead terminal;

forming a second standing piece at the anode lead terminal of the lead frame;

forming a first standing piece at each of the anode lead terminal and the cathode lead terminal of the lead frame without separating the anode lead terminal and the cathode lead terminal from the respective side frame portions;

mounting a capacitor element onto the anode lead terminal and the cathode lead terminal so that an anode and a cathode of the capacitor element are electrically

connected to the anode lead terminal and the cathode lead terminal, respectively, while the anode contacts the second standing piece;

molding a synthetic resin into a package for hermetically sealing the capacitor element so that the lead terminals are embedded in the package with a surface of each of the lead terminals and an outer surface of each of the first standing pieces exposed; and

separating the anode lead terminal and the cathode lead terminal from the respective side frame portions.